

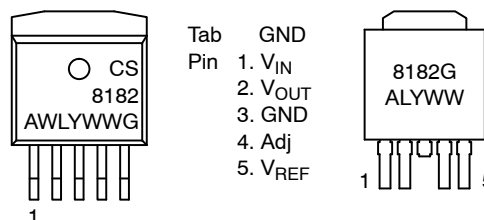
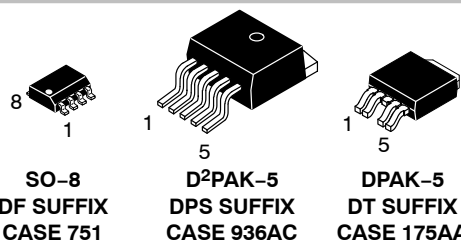
Micropower 200 mA Low Dropout Tracking Regulator/Line Driver

The V_{REF}/ENABLE lead serves two purposes. It is used to provide the input voltage as a reference for the output and it also can be pulled low to place the device in sleep mode where it nominally draws 30 μ A from the supply.

- 200 mA Source Capability
- Output Tracks within ± 10 mV Worst Case
- Low Dropout (0.35 V Typ. @ 200 mA)
- Low Quiescent Current
- Thermal Shutdown
- Short Circuit Protection
- Wide Operating Range
- Internally Fused Leads in SO-8 Package
- For Automotive and Other Applications Requiring Site and Change Control
- These are Pb-Free Devices



<http://onsemi.com>



A = Assembly Location
WL, L = Wafer Lot
Y = Year
WW, W = Work Week
G or ■ = Pb-Free Device

See detailed ordering and shipping information in the package dimensions section on page 9 of this data sheet.

PACKAGE PIN DESCRIPTION

Package Lead Number			Lead Symbol	Function
SO-8	D ² PAK 5-PIN	DPAK 5-PIN		
8	1	1	V _{IN}	Input Voltage
1	2	2	V _{OUT}	Regulated Output
2, 3, 6, 7	3	3	GND	Ground
4	4	4	Adj	Adjust Lead
5	5	5	V _{REF} /ENABLE	Reference Voltage and ENABLE Input

MAXIMUM RATINGS

Rating	Value	Unit
Storage Temperature Range	-65 to +150	°C
Junction Temperature	+150	°C
Supply Voltage Range (Continuous)	-16 to 45	V
Peak Transient Voltage (V _{IN} = 14 V, Load Dump Transient = 31 V)	45	V
Voltage Range (Adj, V _{OUT} , V _{REF} /ENABLE)	-10 to +V _{IN}	V
Package Thermal Resistance, SO-8: Junction-to-Case, R _{θJC} Junction-to-Air, R _{θJA}	25 80	°C/W °C/W
Package Thermal Resistance, D ² PAK Junction-to-Case, R _{θJC} Junction-to-Air, R _{θJA}	4.0 48	°C/W °C/W
Package Thermal Resistance, DPAK Junction-to-Case, R _{θJC} Junction-to-Air, R _{θJA}	8.0 64	°C/W °C/W
ESD Capability (Human Body Model) (Machine Model)	2.0 200	kV V
Lead Temperature Soldering: (Note 1)	(SO-8) (D ² PAK) (DPAK) 240 225 260	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

1. 60 second maximum above 183°C.

RECOMMENDED OPERATING RANGES

Rating	Value	Unit
Junction Temperature, T _J	-40 to +125	°C
Input Voltage, Continuous V _{IN}	3.4 to 45	V

CS8182

ELECTRICAL CHARACTERISTICS ($V_{IN} = 14\text{ V}$; $V_{REF}/ENABLE > 2.75\text{ V}$; $-40^{\circ}\text{C} < T_J < +125^{\circ}\text{C}$; $C_{OUT} \geq 10\text{ }\mu\text{F}$; $0.1\text{ }\Omega < C_{OUT-ESR} < 1.0\text{ }\Omega$ @ 10 kHz , unless otherwise specified.)

Parameter	Test Conditions	Min	Typ	Max	Unit
Regular Output					
$V_{REF} - V_{OUT}$ V_{OUT} Tracking Error	$4.5\text{ V} \leq V_{IN} \leq 26\text{ V}$, $100\text{ }\mu\text{A} \leq I_{OUT} \leq 200\text{ mA}$, Note 2 $V_{IN} = 12\text{ V}$, $I_{OUT} = 30\text{ mA}$, $V_{REF} = 5.0\text{ V}$, Note 2	-10 -5.0	- -	10 5	mV mV
Dropout Voltage ($V_{IN} - V_{OUT}$)	$I_{OUT} = 100\text{ }\mu\text{A}$	-	100	150	mV
	$I_{OUT} = 30\text{ mA}$	-	-	500	mV
	$I_{OUT} = 200\text{ mA}$	-	350	600	mV
Line Regulation	$4.5\text{ V} \leq V_{IN} \leq 26\text{ V}$, Note 2	-	-	10	mV
Load Regulation	$100\text{ }\mu\text{A} \leq I_{OUT} \leq 200\text{ mA}$, Note 2	-	-	10	mV
Adj Lead Current	Loop in Regulation	-	0.2	1.0	μA
Current Limit	$V_{IN} = 14\text{ V}$, $V_{REF} = 5.0\text{ V}$, $V_{OUT} = 90\%$ of V_{REF} , Note 2	250	-	700	mA
Quiescent Current ($I_{IN} - I_{OUT}$)	$V_{IN} = 12\text{ V}$, $I_{OUT} = 200\text{ mA}$	-	15	25	mA
	$V_{IN} = 12\text{ V}$, $I_{OUT} = 100\text{ }\mu\text{A}$	-	75	150	μA
	$V_{IN} = 12\text{ V}$, $V_{REF}/ENABLE = 0\text{ V}$	-	30	55	μA
Reverse Current	$V_{OUT} = 5.0\text{ V}$, $V_{IN} = 0\text{ V}$	-	0.2	1.5	mA
Ripple Rejection	$f = 120\text{ Hz}$, $I_{OUT} = 200\text{ mA}$, $4.5\text{ V} \leq V_{IN} \leq 26\text{ V}$	60	-	-	dB
Thermal Shutdown	GBD	150	180	210	$^{\circ}\text{C}$
$V_{REF}/ENABLE$					
Enable Voltage	-	0.80	2.00	2.75	V
Input Bias Current	$V_{REF}/ENABLE$	-	0.2	1.0	μA

2. V_{OUT} connected to Adj lead.

TYPICAL CHARACTERISTICS

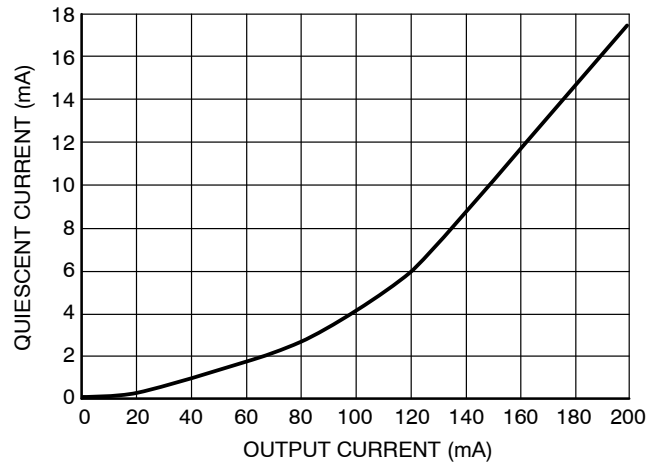


Figure 2. Quiescent Current vs. Output Current

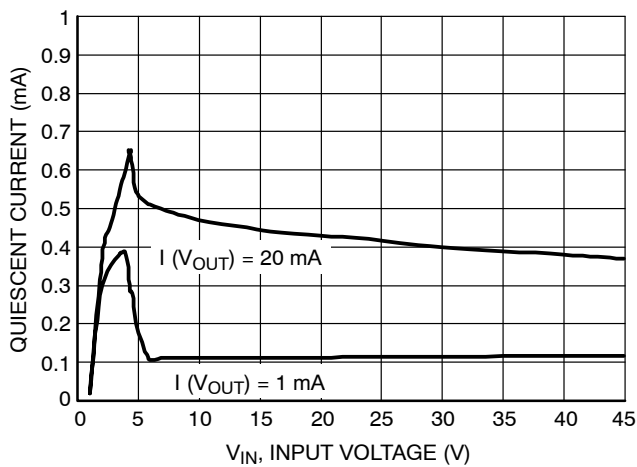


Figure 3. Quiescent Current vs. Input Voltage (Operating Mode)

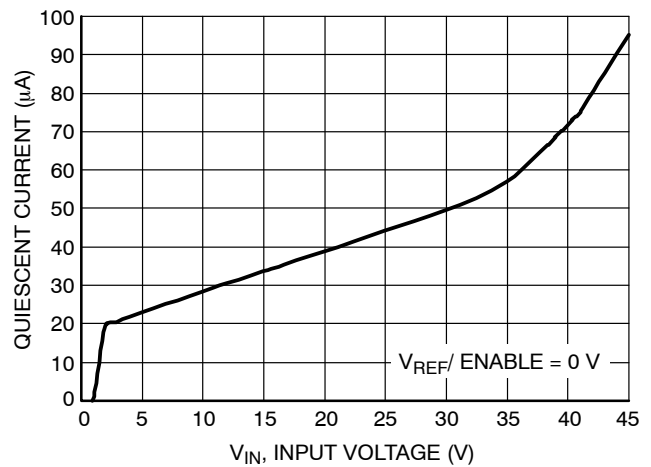
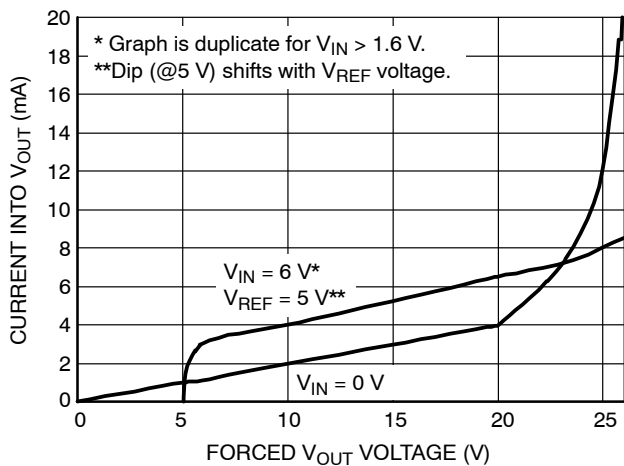
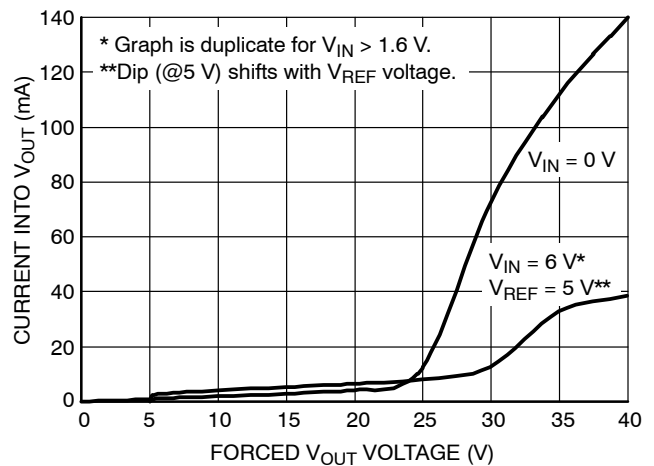


Figure 4. Quiescent Current vs. Input Voltage (Sleep Mode)

Figure 5. V_{OUT} Reverse CurrentFigure 6. V_{OUT} Reverse Current

CIRCUIT DESCRIPTION

ENABLE Function

By pulling the $V_{REF}/ENABLE$ lead below 2.0 V typically, (see Figure 10 or Figure 11), the IC is disabled and enters a sleep state where the device draws less than 55 μA from supply. When the $V_{REF}/ENABLE$ lead is greater than 2.75 V, V_{OUT} tracks the $V_{REF}/ENABLE$ lead normally.

Output Voltage

The output is capable of supplying 200 mA to the load while configured as a similar (Figure 7), lower (Figure 9), or higher (Figure 8) voltage as the reference lead. The Adj lead acts as the inverting terminal of the op amp and the V_{REF} lead as the non-inverting.

The device can also be configured as a high-side driver as displayed in Figure 12.

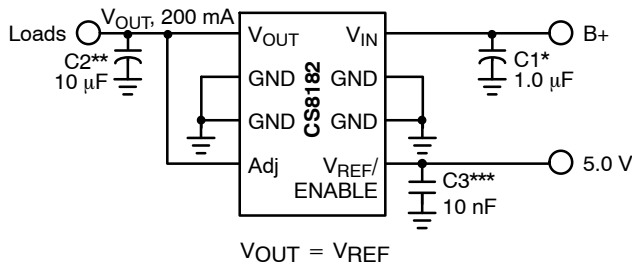


Figure 7. Tracking Regulator at the Same Voltage

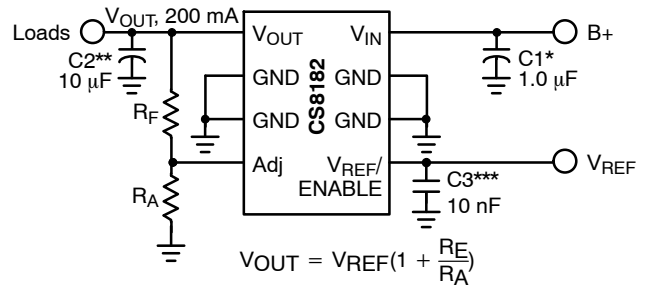


Figure 8. Tracking Regulator at Higher Voltages

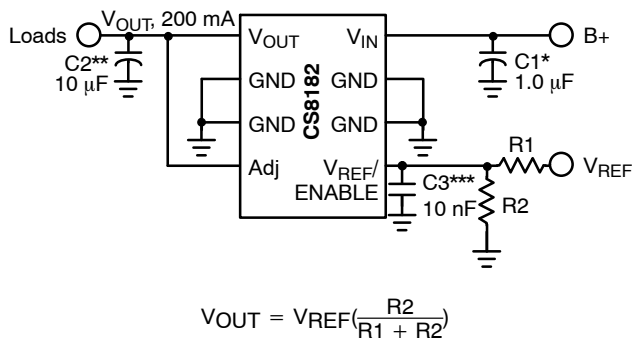


Figure 9. Tracking Regulator at Lower Voltages

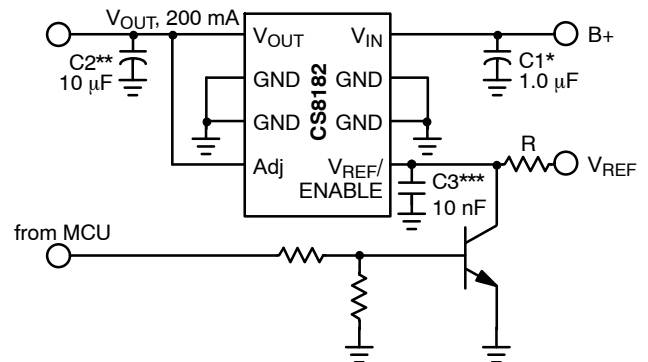


Figure 10. Tracking Regulator with ENABLE Circuit

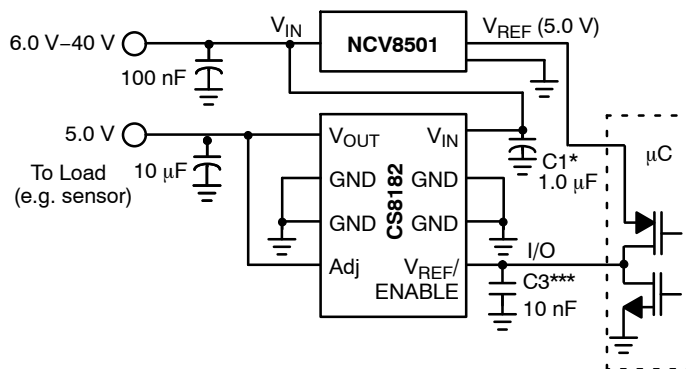


Figure 11. Alternative ENABLE Circuit

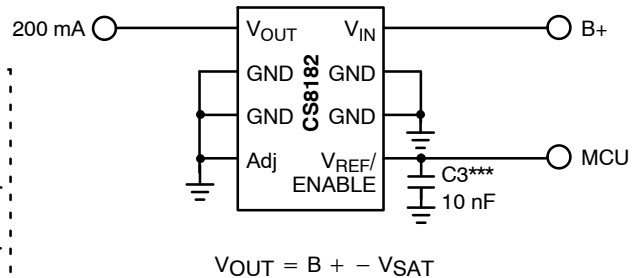


Figure 12. High-Side Driver

* C1 is required if the regulator is far from the power source filter.

** C2 is required for stability.

*** C3 is recommended for EMC susceptibility.

APPLICATION NOTES

V_{OUT} Short to Battery

The CS8182 will survive a short to battery when hooked up the conventional way as shown in Figure 13. No damage to the part will occur. The part also endures a short to battery when powered by an isolated supply at a lower voltage as in

Figure 14. In this case the CS8182 supply input voltage is set at 7 V when a short to battery (14 V typical) occurs on V_{OUT} which normally runs at 5 V. The current into the device (ammeter in Figure 14) will draw additional current as displayed in Figure 15.

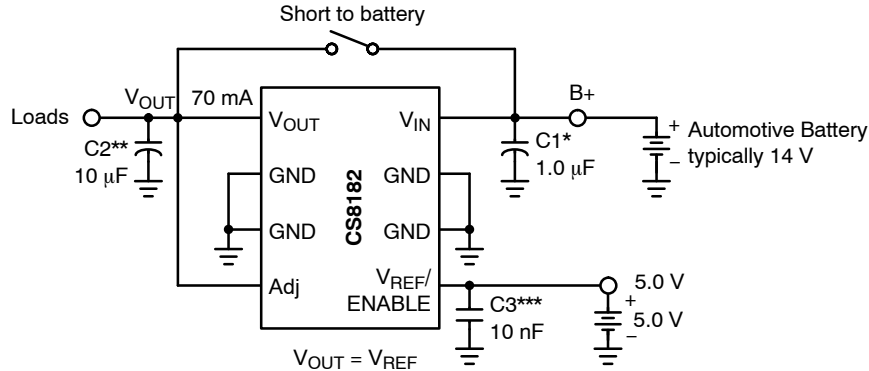
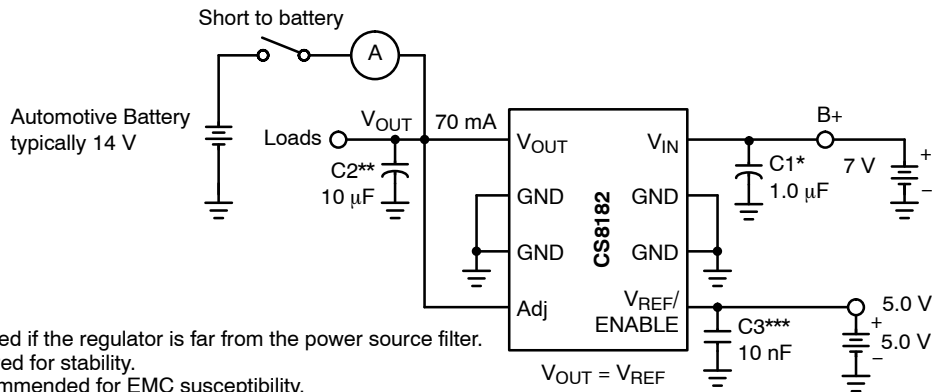


Figure 13.



* C1 is required if the regulator is far from the power source filter.
 ** C2 is required for stability.
 *** C3 is recommended for EMC susceptibility.

Figure 14.



Figure 15. V_{OUT} Short to Battery

Switched Application

The CS8182 has been designed for use in systems where the reference voltage on the V_{REF}/ENABLE pin is continuously on. Typically, the current into the V_{REF}/ENABLE pin will be less than 1.0 μA when the voltage on the V_{IN} pin (usually the ignition line) has been switched out (V_{IN} can be at high impedance or at ground.) Reference Figure 16.

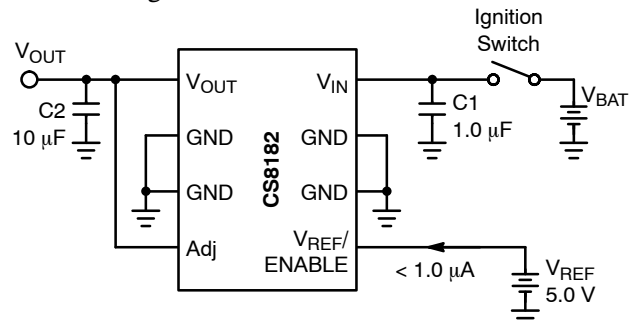


Figure 16.

External Capacitors

The output capacitor for the CS8182 is required for stability. Without it, the regulator output will oscillate. Actual size and type may vary depending upon the application load and temperature range. Capacitor effective series resistance (ESR) is also a factor in the IC stability. Worst-case is determined at the minimum ambient temperature and maximum load expected.

The output capacitor can be increased in size to any desired value above the minimum. One possible purpose of this would be to maintain the output voltage during brief conditions of negative input transients that might be characteristic of a particular system.

The capacitor must also be rated at all ambient temperatures expected in the system. To maintain regulator stability down to -40°C , a capacitor rated at that temperature must be used.

Calculating Power Dissipation in a Single Output Linear Regulator

The maximum power dissipation for a single output regulator (Figure 17) is:

$$\text{PD(max)} = \{V_{\text{IN(max)}} - V_{\text{OUT(min)}}\} I_{\text{OUT(max)}} + V_{\text{IN(max)}} I_{\text{Q}} \quad (1)$$

where:

$V_{\text{IN(max)}}$ is the maximum input voltage,

$V_{\text{OUT(min)}}$ is the minimum output voltage,

$I_{\text{OUT(max)}}$ is the maximum output current, for the application, and

I_{Q} is the quiescent current the regulator consumes at $I_{\text{OUT(max)}}$.

Once the value of PD(max) is known, the maximum permissible value of $R_{\theta\text{JA}}$ can be calculated:

$$R_{\theta\text{JA}} = \frac{150^{\circ}\text{C} - T_{\text{A}}}{\text{PD}} \quad (2)$$

The value of $R_{\theta\text{JA}}$ can then be compared with those in the package section of the data sheet. Those packages with $R_{\theta\text{JA}}$'s less than the calculated value in equation 2 will keep the die temperature below 150°C .

In some cases, none of the packages will be sufficient to dissipate the heat generated by the IC, and an external heat sink will be required.

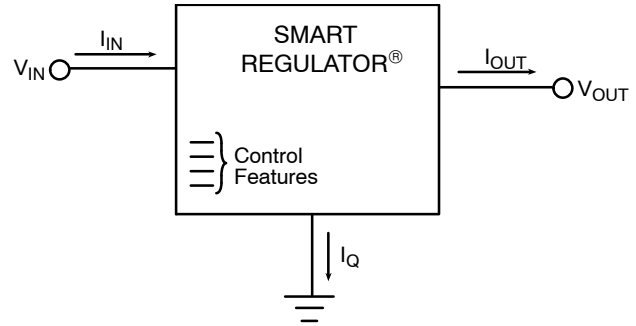


Figure 17. Single Output Regulator with Key Performance Parameters Labeled

Heatsinks

A heatsink effectively increases the surface area of the package to improve the flow of heat away from the IC and into the surrounding air.

Each material in the heat flow path between the IC and the outside environment will have a thermal resistance. Like series electrical resistances, these resistances are summed to determine the value of $R_{\theta\text{JA}}$:

$$R_{\theta\text{JA}} = R_{\theta\text{JC}} + R_{\theta\text{CS}} + R_{\theta\text{SA}} \quad (3)$$

where:

$R_{\theta\text{JC}}$ = the junction-to-case thermal resistance,

$R_{\theta\text{CS}}$ = the case-to-heatsink thermal resistance, and

$R_{\theta\text{SA}}$ = the heatsink-to-ambient thermal resistance.

$R_{\theta\text{JC}}$ appears in the package section of the data sheet. Like $R_{\theta\text{JA}}$, it is a function of package type. $R_{\theta\text{CS}}$ and $R_{\theta\text{SA}}$ are functions of the package type, heatsink and the interface between them. These values appear in heat sink data sheets of heatsink manufacturers.

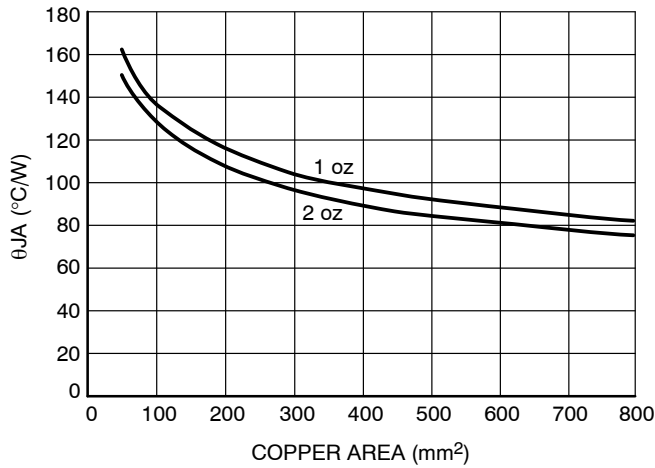


Figure 18. 8 Lead SOIC (Fused) Thermal Resistance

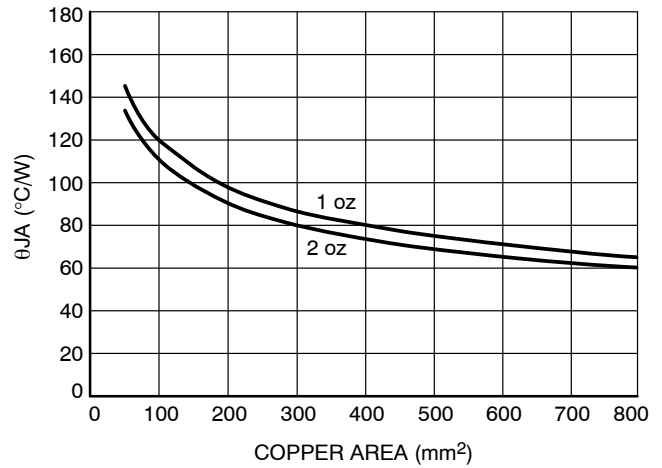


Figure 19. 5 Lead DPAK Thermal Resistance

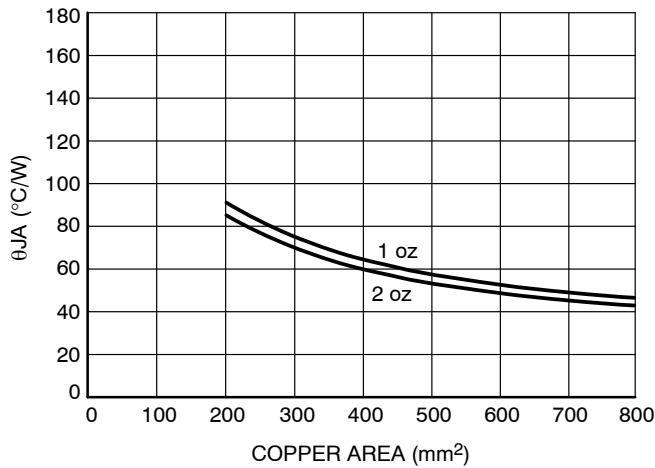


Figure 20. 5 Lead D²PAK Thermal Resistance

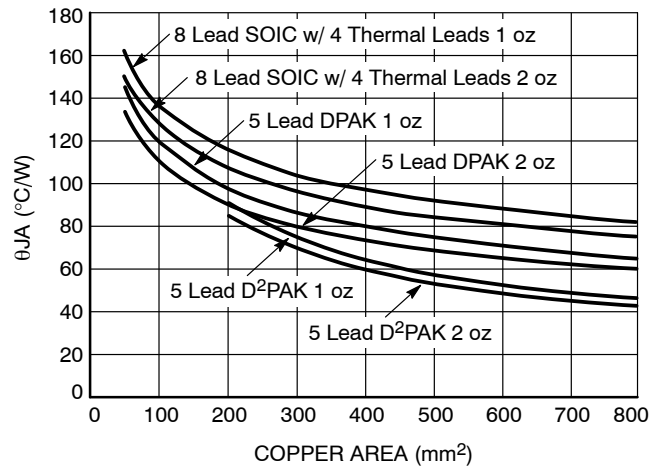


Figure 21. Thermal Resistance Summary

CS8182

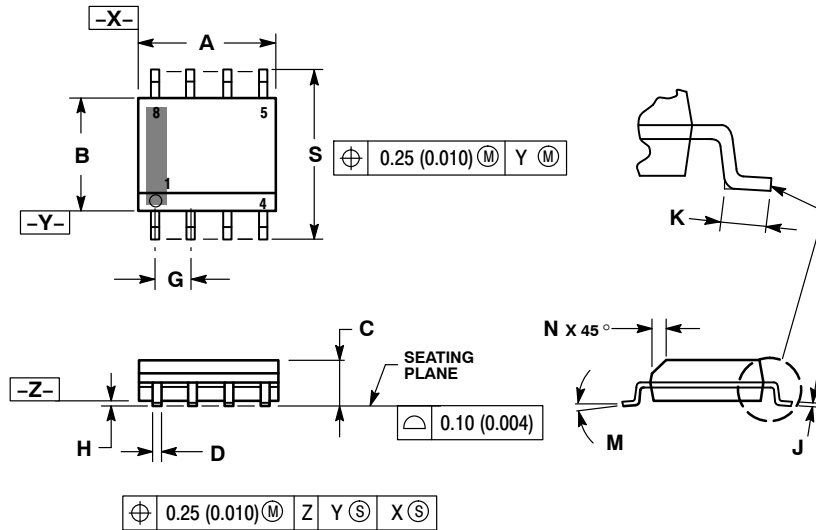
ORDERING INFORMATION

Device	Package	Shipping [†]
CS8182YDF8G	SO-8 (Pb-Free)	95 Units / Rail
CS8182YDFR8G	SO-8 (Pb-Free)	2500 / Tape & Reel
CS8182YDPS5G	D ² PAK 5-PIN (Pb-Free)	50 Units / Rail
CS8182YDPSR5G	D ² PAK 5-PIN (Pb-Free)	750 / Tape & Reel
CS8182DTG	DPAK 5L (Pb-Free)	50 Units / Rail
CS8182DTRKG	DPAK 5L (Pb-Free)	2500 / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

PACKAGE DIMENSIONS

SOIC-8
DF SUFFIX
CASE 751-07
ISSUE AK

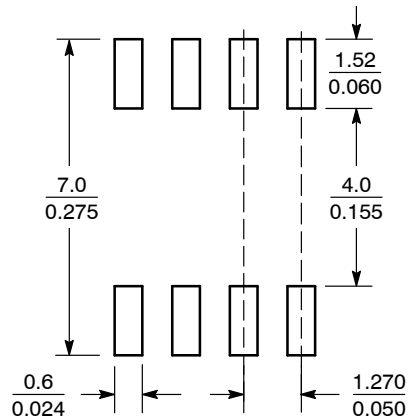


NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSION A AND B DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.
6. 751-01 THRU 751-06 ARE OBSOLETE. NEW STANDARD IS 751-07.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	4.80	5.00	0.189	0.197
B	3.80	4.00	0.150	0.157
C	1.35	1.75	0.053	0.069
D	0.33	0.51	0.013	0.020
G	1.27 BSC		0.050 BSC	
H	0.10	0.25	0.004	0.010
J	0.19	0.25	0.007	0.010
K	0.40	1.27	0.016	0.050
M	0°	8°	0°	8°
N	0.25	0.50	0.010	0.020
S	5.80	6.20	0.228	0.244

SOLDERING FOOTPRINT*

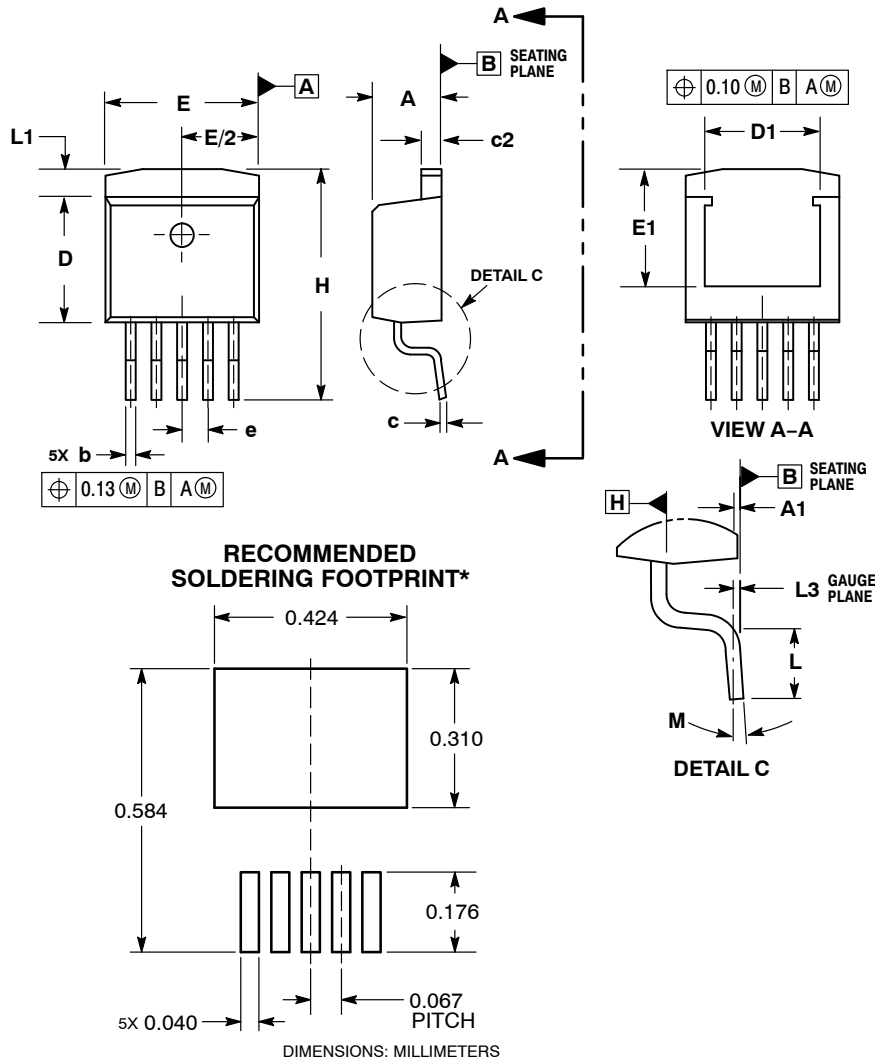


SCALE 6:1 ($\frac{\text{mm}}{\text{inches}}$)

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

PACKAGE DIMENSIONS

D²PAK-5
DP SUFFIX
CASE 936AC
ISSUE A



NOTES:

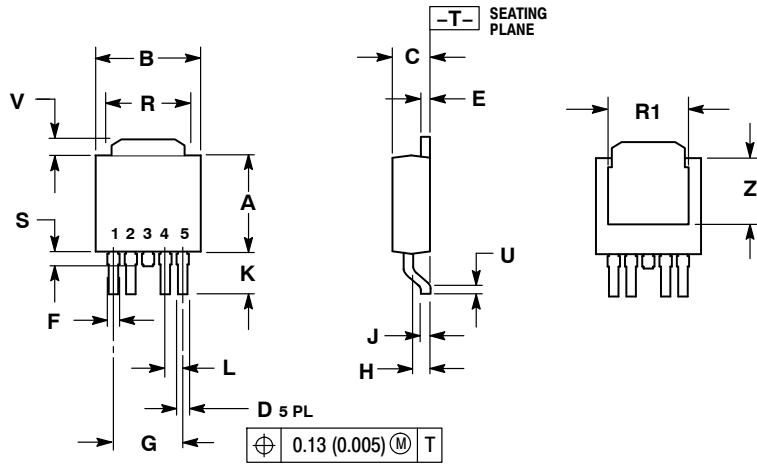
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: INCHES.
3. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH AND GATE PROTRUSIONS. MOLD FLASH AND GATE PROTRUSIONS NOT TO EXCEED 0.005 MAXIMUM PER SIDE. THESE DIMENSIONS TO BE MEASURED AT DATUM H.
4. THERMAL PAD CONTOUR OPTIONAL WITHIN DIMENSIONS E, L1, D1, AND E1. DIMENSIONS D1 AND E1 ESTABLISH A MINIMUM MOUNTING SURFACE FOR THE THERMAL PAD.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.170	0.180	4.32	4.57
A1	0.000	0.010	0.00	0.25
b	0.026	0.036	0.66	0.91
c	0.017	0.026	0.43	0.66
c2	0.045	0.055	1.14	1.40
D	0.325	0.368	8.25	9.53
D1	0.250	---	6.35	---
E	0.380	0.420	9.65	10.67
E1	0.200	---	5.08	---
e	0.067 BSC		1.70 BSC	
H	0.580	0.620	14.73	15.75
L	0.090	0.110	2.29	2.79
L1	---	0.066	---	1.68
L3	0.010 BSC		0.25 BSC	
M	0 °		8 °	

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

PACKAGE DIMENSIONS

DPAK-5
DT SUFFIX
CASE 175AA
ISSUE A

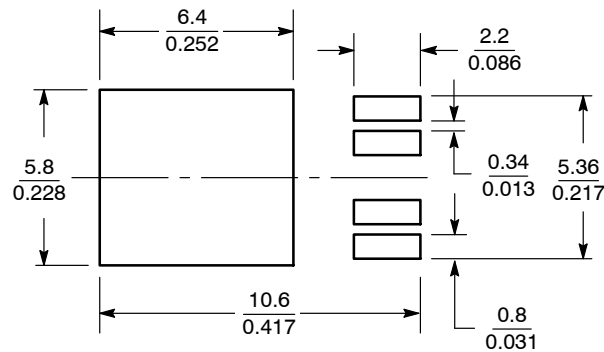


NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.235	0.245	5.97	6.22
B	0.250	0.265	6.35	6.73
C	0.086	0.094	2.19	2.38
D	0.020	0.028	0.51	0.71
E	0.018	0.023	0.46	0.58
F	0.024	0.032	0.61	0.81
G	0.180 BSC		4.56 BSC	
H	0.034	0.040	0.87	1.01
J	0.018	0.023	0.46	0.58
K	0.102	0.114	2.60	2.89
L	0.045 BSC		1.14 BSC	
R	0.170	0.190	4.32	4.83
R1	0.185	0.210	4.70	5.33
S	0.025	0.040	0.63	1.01
U	0.020	---	0.51	---
V	0.035	0.050	0.89	1.27
Z	0.155	0.170	3.93	4.32

SOLDERING FOOTPRINT*



SCALE 4:1 $\left(\frac{\text{mm}}{\text{inches}} \right)$

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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- Экспресс доставка в любую точку России;
- Техническая поддержка проекта, помощь в подборе аналогов, поставка прототипов;
- Система менеджмента качества сертифицирована по Международному стандарту ISO 9001;
- Лицензия ФСБ на осуществление работ с использованием сведений, составляющих государственную тайну;
- Поставка специализированных компонентов (Xilinx, Altera, Analog Devices, Intersil, Interpoint, Microsemi, Aeroflex, Peregrine, Syfer, Eurofarad, Texas Instrument, Miteq, Cobham, E2V, MA-COM, Hittite, Mini-Circuits, General Dynamics и др.);

Помимо этого, одним из направлений компании «ЭлектроПласт» является направление «Источники питания». Мы предлагаем Вам помощь Конструкторского отдела:

- Подбор оптимального решения, техническое обоснование при выборе компонента;
- Подбор аналогов;
- Консультации по применению компонента;
- Поставка образцов и прототипов;
- Техническая поддержка проекта;
- Защита от снятия компонента с производства.



Как с нами связаться

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